

SECTION II—CLAIMS

1. (Currently Amended) An apparatus comprising:

a die mounted on a substrate, the die being connected to the substrate by a plurality of wires; and

a mold cap encapsulating the die and the plurality of wires, the mold cap comprising an electrically insulating portion encapsulating substantially all the wires and the entire die, and a thermally conductive portion encapsulating substantially all the electrically insulating portion, wherein the thermally conductive ~~material~~ portion is in contact only with the substrate and [[with]] the entire part of the surface of the electrically insulating ~~material~~ portion that is not in contact with the substrate, the die or the wires.

2. (Original) The apparatus of claim 1 wherein the die comprises an integrated circuit.
3. (Original) The apparatus of claim 1 wherein the electrically insulating material comprises a curable resin, a crosslinker, a catalyst, and a reinforcing filler.
4. (Original) The apparatus of claim 3 wherein the reinforcing filler comprises silica, alumina, zinc oxide, talc, or combinations thereof.
5. (Original) The apparatus of claim 1 wherein the thermally conductive material comprises a curable resin, a crosslinker, a catalyst, and a metal filler.
6. (Original) The apparatus of claim 5 wherein the metal filler comprises aluminum, silver, copper, gold, or combinations or alloys thereof.
- 7.-8. (Canceled)

9. (Original) The apparatus of claim 1, further comprising a heat dissipation device attached to, and in thermal contact with, the thermally conductive material.

10.-51. (Canceled)